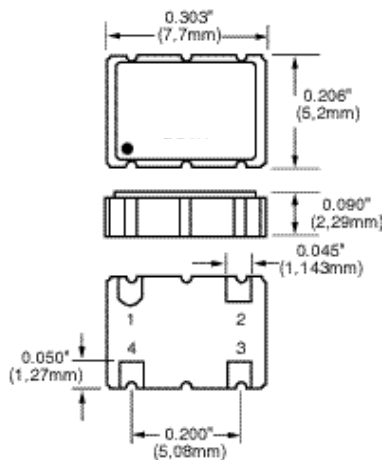
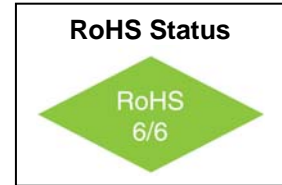


VF3 XO Low Jitter 5x7mm SMD, HCMOS-TTL



Features

- HCMOS – TTL Compatible
- 3.3V Supply Voltage
- 5% Duty Cycle
- Tristate control standard



All dimensions are typical unless otherwise specified.

Electrical Connections

Pin #	Function
Pin 1	Tristate Control
Pin 2	Ground
Pin 3	Output
Pin 4	Vcc

Creating a Part Number

VF3 - - FREQ

Frequency Stability	
Code	Specification
S	±20 ppm
A	±25 ppm
B	±50 ppm
	±100 ppm

Oper. Temp. Range	
Code	Specification
	-10°C to 70°C
1	-40°C to +85°C

Duty Cycle	
Code	Specification
H	±5%
	±10%

Parameter	Symb	Condition	Min	Typ	Max	Unit	Note
Input Break Down Voltage	V _{cc}		-0.5		7.0	V	
Storage Temp.	T _s		-55		+125	°C	
Frequency Range	F		1.8		160	MHz	
Frequency Stability	ΔF/F	Overall conditions including: calibration, temp., aging 10 yrs, shock, vibration			±100	ppm	1
Input Voltage	V _{cc}		3.15	3.30	3.45	V	
Input Current	I _{cc}	15pF load			10 15 18 28	mA	to 25MHz to 50MHz to 67MHz to 125MHz
Load	10 LSTTL gates or 15pF Typ, 30pF Max.						
Duty Cycle		@50% V _{cc}	45 40	50 50	55 60	%	to 50MHz
Rise / Fall Time	Tr/Tf	10% to 90%		5	10	ns	
Logic "1" Level	V _{oh}	Max Load	0.9V _c			V	
Logic "0" Level	V _{ol}	Max Load			0.1V _c	V	
Start-up Time	T _s			3	10	ms	
Phase Jitter		1σ		0.5	1	ps	f _j >1KHz
Tristate Function	Input HIGH (>2.5V) or floating: Active Input LOW (0.5V): Infinite Impedance						
Operating Temperature Range	-10°C to +70°C (-40°C to +85°C available)						
Mechanical Shock	Per MIL-STD-202, Method 213, Cond. E						
Thermal Shock	Per MIL-STD-883, Method 1011, Cond. A						
Vibration	Per MIL-STD-883, Method 2007, Cond. A						
Soldering Conditions	260°C for 10s Max., or 230°C for 90s						
Hermetic Seal	Leak rate less than 5 x 10 ⁻⁸ atm.cc/s of helium						

